

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples. Alternatively, you may send an email request for data, samples or other information to PCNSupport@fairchildsemi.com.

Implementation of change:

Expected First Shipment Date for Changed Product : Jul. 28, 2013

Expected First Date Code of Changed Product :1330

Description of Change (From) :

Devices listed in the affected products list are manufactured on the 6 inch wafer fabrication line located in Fairchild Semiconductor Salt Lake Fab and/or manufactured on the 8 inch wafer fabrication line at the TSMC foundry.

Description of Change (To) :

Devices listed in the affected products list are manufactured on the 6 inch wafer fabrication line located in Fairchild Semiconductor Salt Lake Fab and/or manufactured on the 8 inch wafer fabrication line at the TSMC foundry. In addition, devices listed in the affected products list will also be manufactured at the alternative 8 inch wafer fabrication line at the Vanguard International Semiconductor Corporation foundry in Taiwan.

Reason for Change:

Fairchild Semiconductor is increasing wafer capacity by qualifying the process for the affected products at Vanguard International Semiconductor Corporation, Taiwan. Quality and reliability will remain at the highest standards already demonstrated with Fairchild's existing products. The reliability qualification results used to qualify the wafer fabrication line is summarized below. This is in addition to specific products already qualified at our Vanguard wafer fabrication foundry. The specific groups of products/MOSFET technologies are listed in the affected products list. Design, die size, and layout of the affected products will remain unchanged. There are no changes in the datasheet or electrical performance between products manufactured at the current or the alternative wafer fabrication lines. Products from the two fabrication lines may be shipped interchangeably.

Affected Product(s):

FDMC0310AS	FDMC0310AS F127	FDMC7672S
FDMC8026S	FDMS0300S	FDMS0302S
FDMS0306AS	FDMS0308AS	FDMS0309AS
FDMS0310AS	FDMS0312AS	FDMS0312S
FDMS7602S	FDMS7608S	FDMS7656AS
FDMS7658AS	FDMS7694 SN00251	FDMS8023S
FDMS8025AS	FDMS8025S	FDMS8026S
FDMS8027S		

Qualification Plan	Device	Package	Process	No. of Lots
QP12120985G	FDMS0300S	PQFN 5x6	QR08CFZ8TNSA8	3

Test Description:	Condition:	Standard :	Duration:	Results:
MSL1 Precondition	260°C, 3 pass	JESD22-A113		0/462
Highly Accelerated Stress Test	130°C, 85%RH, Vr = 24V	JESD22-A110	96 hours	0/231
High Temperature Storage Life	175°C	JESD22-A103	500 hours	0/231
Power Cycle	T on/off = 2min, Delta Tj = 100°C	JESD22-A105	10000 cycles	0/231
Temperature Cycle	-65°C to 150°C, 15min dwell	JESD22-A104	500 cycles	0/231
High Temperature Reverse Bias	125°C, Vr = 24V	JESD22-A108	1000 hours	0/231
High Temperature Gate Bias	150°C, Vgs = 20V	JESD22-A108-B	1000 hours	0/231